



BSI Standards Publication

Test methods for electrical materials, printed boards and other interconnection structures and assemblies

Part 2-807: Test methods for materials for interconnection structures — Decomposition temperature (T_d) using TGA

National foreword

This British Standard is the UK implementation of EN IEC 61189-2-807:2021. It is identical to IEC 61189-2-807:2021.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Amendments/corrigenda issued since publication

Date	Text affected
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English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies - Part 2-807: Test
methods for materials for interconnection structures -
Decomposition temperature (T_d) using TGA
(IEC 61189-2-807:2021)

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-807: Méthodes d'essai des matériaux
pour structures d'interconnexion - Température de
décomposition (T_d) par analyse thermogravimétrique
(IEC 61189-2-807:2021)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 2-
807: Prüfverfahren für Materialien für
Verbindungsstrukturen - Zersetzungstemperatur (T_d) unter
der Nutzung von TGA
(IEC 61189-2-807:2021)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 91/1697/CDV, future edition 1 of IEC 61189-2-807, prepared by IEC/TC 91 “Electronics assembly technology” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61189-2-807:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2022-07-08 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2024-10-08 document have to be withdrawn

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Endorsement notice

The text of the International Standard IEC 61189-2-807:2021 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and-assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies		-
ISO 11358-1	-	Plastics - Thermogravimetry (TG) of polymers - Part 1: General principles	ofEN ISO 11358-1	-